



CofC

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q83383

Ken SAKATA, et al.

Group Art Unit: 1775

Appln. No.: 10/507,242

Examiner: Cathy Fong Fong LAM

Confirmation No.: 9079

Patent No.: 7,255,919

Filed: September 10, 2004

Issue Date: August 14, 2007

For: MOLD RELEASING LAYER TRANSFER FILM AND LAMINATE FILM

REQUEST FOR CERTIFICATE OF CORRECTION

ATTN: Certificate of Correction Branch

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Certificate
NOV 02 2007
of Correction

Sir:

Pursuant to the provisions of 37 C.F.R. § 1.322, please enter the attached Certificate of Correction.

Since the errors noted are believed to be the fault of the Patent and Trademark Office, we are not enclosing the \$100.00 Certificate of Correction fee. If it is found to be to the contrary, please charge our Deposit Account No. 19-4880.

In view of the foregoing, issuance of the Certificate of Correction is respectfully requested.

Respectfully submitted,

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WASHINGTON OFFICE

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CUSTOMER NUMBER

Date: October 30, 2007

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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO: 7,255,919
DATED: August 14, 2007
INVENTOR(S): Ken SAKATA and Katsuhiko HAYASHI

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

1. A releasing layer transfer film for forming a releasing layer onto an insulating layer serving as a component of a chip-on-film (COF) flexible printed wiring board, characterized in that the releasing layer transfer film comprises a transfer film substrate, and a transferable releasing layer provided on a surface of the transfer film substrate, wherein the transferable releasing layer is formed from a releasing agent comprising a silazane compound and can be transferred onto the insulating layer.

14. A method for producing a COF flexible printed wiring board, the method comprising
laminating, onto an insulating layer serving as a component of a COF flexible printed wiring board, a releasing layer transfer film comprising a transfer film substrate, and a transferable releasing layer provided on a surface of the transfer film substrate, such that the transferable releasing layer is laminated on the insulating layer;
forming a wiring pattern ~~from a~~ in a conductor layer provided on the surface of the insulating layer opposite the surface on which the releasing layer transfer film has been laminated to thereby produce a COF flexible printed wiring board; and
peeling the transfer film substrate, to thereby transfer the transferable releasing layer onto the insulating layer, whereby a COF flexible printed wiring board having a releasing layer on the insulating layer is produced;
wherein the releasing layer is formed from a releasing agent containing at least one species selected from a silane compound, a silica sol and a silazane compound, and the insulating layer serves as a member of a COF flexible printed wiring board.

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PATENT NO. 7,255,919

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